LM124
LM224 - LM324

LOW POWER QUAD OPERATIONAL AMPLIFIERS

- WIDE GAIN BANDWIDTH : 1.3MHz
- INPUT COMMON-MODE VOLTAGE RANGE INCLUDES GROUND
- LARGE VOLTAGE GAIN : 100dB
- VERY LOW SUPPLY CURRENT/AMPLI : 375µA
- LOW INPUT BIAS CURRENT : 20nA
- LOW INPUT OFFSET VOLTAGE : 5mV max. (for more accurate applications, use the equivalent parts LM124A-LM224A-LM324A which feature 3mV max.)
- LOW INPUT OFFSET CURRENT : 2nA
- WIDE POWER SUPPLY RANGE : SINGLE SUPPLY : +3V TO +30V DUAL SUPPLIES : ±1.5V TO ±15V

N
DIP14
(Plastic Package)

D
SO14
(Plastic Micropackage)

P
TSSOP14
(Thin Shrink Small Outline Package)

DESCRIPTION

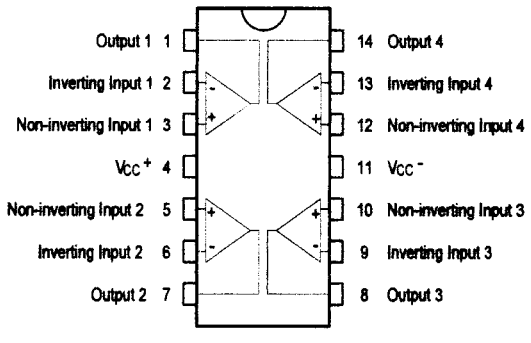
These circuits consist of four independent, high gain, internally frequency compensated operational amplifiers. They operate from a single power supply over a wide range of voltages. Operation from split power supplies is also possible and the low power supply current drain is independent of the magnitude of the power supply voltage.

ORDER CODE

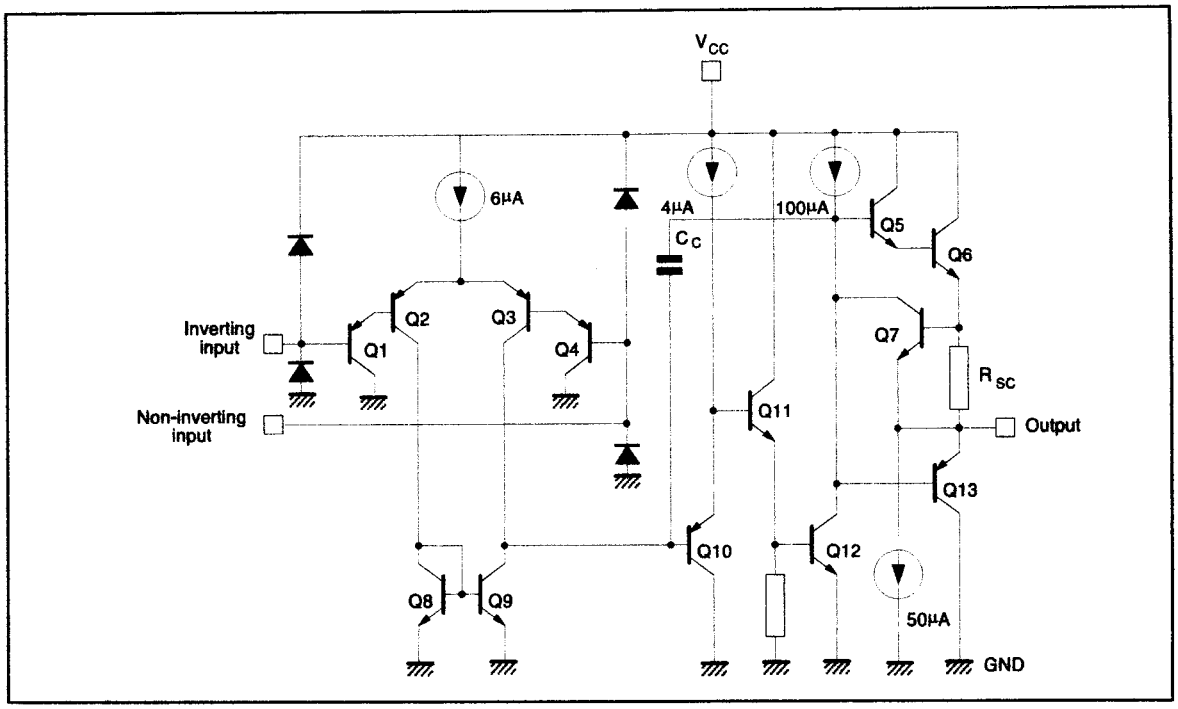
Part Number	Temperature Range	Package		
		N	D	P
LM124	-55°C, +125°C	•	•	•
LM224	-40°C, +105°C	•	•	•
LM324	0°C, +70°C	•	•	•
Example : LM224N				

N = Dual in Line Package (DIP)
D = Small Outline Package (SO) - also available in Tape & Reel (DT)
P = Thin Shrink Small Outline Package (TSSOP) - only available in Tape &Reel (PT)

PIN CONNECTIONS (top view)



SCHEMATIC DIAGRAM (1/4 LM124)



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	LM124	LM224	LM324	Unit
V_{CC}	Supply voltage	±16 or 32			V
V_i	Input Voltage	-0.3 to +32			V
V_{id}	Differential Input Voltage [1]	+32			V
P_{tot}	Power Dissipation N Suffix D Suffix	500	500 400	500 400	mW mW
	Output Short-circuit Duration [2]	Infinite			
I_{in}	Input Current [3]	50	50	50	mA
T_{oper}	Opearting Free-air Temperature Range	-55 to +125	-40 to +105	0 to +70	°C
T_{stg}	Storage Temperature Range	-65 to +150			°C

1. Either or both input voltages must not exceed the magnitude of V_{CC}^+ or V_{CC}^-.
2. Short-circuits from the output to VCC can cause excessive heating if V_{CC} > 15V. The maximum output current is approximately 40mA independent of the magnitude of V_{CC}. Destructive dissipation can result from simultaneous short-circuit on all amplifiers.
3. This input current only exists when the voltage at any of the input leads is driven negative. It is due to the collector-base junction of the input PNP transistor becoming forward biased and thereby acting as input diodes clamps. In addition to this diode action, there is also NPN parasitic action on the IC chip. this transistor action can cause the output voltages of the Op-amps to go to the V_{CC} voltage level (or to ground for a large overdrive) for the time duration than an input is driven negative.
This is not destructive and normal output will set up again for input voltage higher than -0.3V.

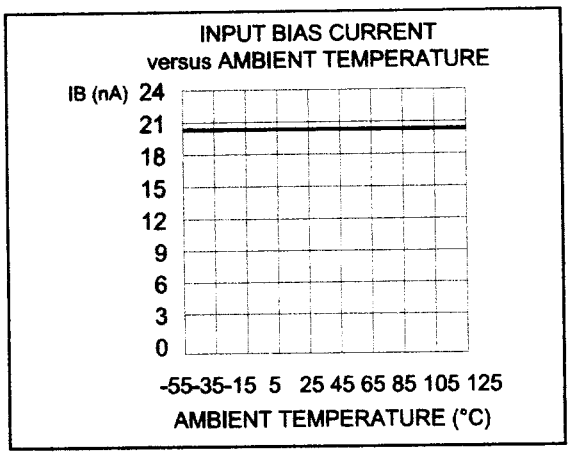
ELECTRICAL CHARACTERISTICS

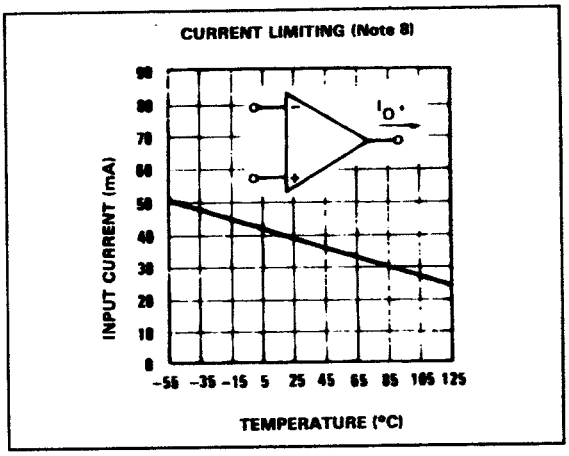
V_{CC}^+ = +5V, V_{CC}^-= Ground, V_o = 1.4V, T_{amb} = +25°C (unless otherwise specified)

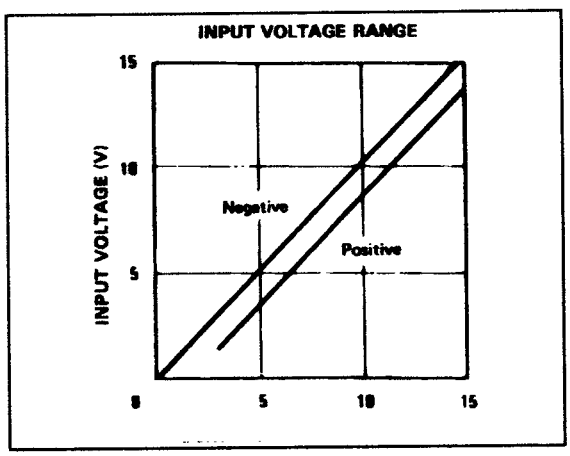
Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{io}	Input Offset Voltage - note 1) T_{amb} = +25°C LM324 $T_{min} \le T_{amb} \le T_{max}$ LM324		2	5 7 7 9	mV
I_{io}	Input Offset Current T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$		2	30 100	nA
I_{ib}	Input Bias Current - note 2) T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$		20	150 300	nA
A_{vd}	Large Signal Voltage Gain V_{CC}^+ = +15V, R_L = 2kΩ, V_o = 1.4V to 11.4V T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$	 50 25	100		V/mV
SVR	Supply Voltage Rejection Ratio ($R_s \le 10k\Omega$) V_{CC}^+ = 5V to 30V T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$	 65 65	110		dB
I_{CC}	Supply Current, all Amp, no load T_{amb} = +25°C V_{CC} = +5V V_{CC} = +30V $T_{min} \le T_{amb} \le T_{max}$ V_{CC} = +5V V_{CC} = +30V		 0.7 1.5 0.8 1.5	 1.2 3 1.2 3	mA
V_{icm}	Input Common Mode Voltage Range V_{CC} = +30V - note 3) T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$	 0 0		 V_{CC} -1.5 V_{CC} -2	V
CMR	Common Mode Rejection Ratio ($R_s \le 10k\Omega$) T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$	 70 60	80		dB
I_{source}	Output Current Source (V_{id} = +1V) V_{CC} = +15V, V_o = +2V	20	40	70	mA
I_{sink}	Output Sink Current (V_{id} = -1V) V_{CC} = +15V, V_o = +2V V_{CC} = +15V, V_o = +0.2V	 10 12	 20 50		 mA µA
V_{OH}	High Level Output Voltage V_{CC} = +30V T_{amb} = +25°C R_L = 2kΩ $T_{min} \le T_{amb} \le T_{max}$ T_{amb} = +25°C R_L = 10kΩ $T_{min} \le T_{amb} \le T_{max}$ V_{CC} = +5V, R_L = 2kΩ T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$	 26 26 27 27 3.5 3	 27 28		V

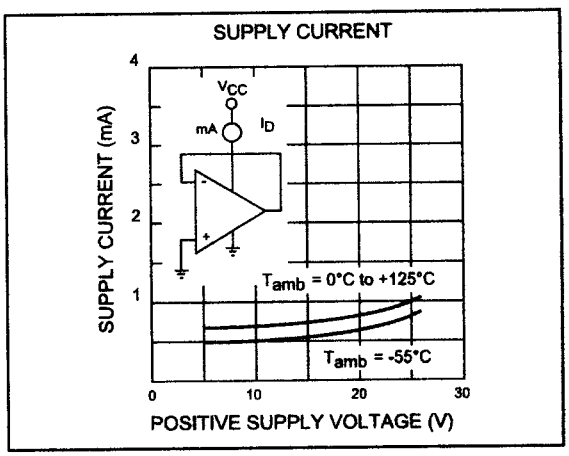
Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{OL}	Low Level Output Voltage (R_L = 10kΩ) T_{amb} = +25°C $T_{min} \le T_{amb} \le T_{max}$		5	20 20	mV
SR	Slew Rate V_{CC} = 15V, V_i = 0.5 to 3V, R_L = 2kΩ, C_L = 100pF, unity Gain		0.4		V/µs
GBP	Gain Bandwidth Product V_{CC} = 30V, f =100kHz,V_{in} = 10mV, R_L = 2kΩ, C_L = 100pF		1.3		MHz
THD	Total Harmonic Distortion f = 1kHz, A_v = 20dB, R_L = 2kΩ, V_o = $2V_{pp}$, C_L = 100pF, V_{CC} = 30V		0.015		%
e_n	Equivalent Input Noise Voltage f = 1kHz, R_s = 100Ω, V_{CC} = 30V		40		$\frac{nV}{\sqrt{Hz}}$
DV_{io}	Input Offset Voltage Drift		7	30	µV/°C
DI_{io}	Input Offset Current Drift		10	200	pA/°C
V_{o1}/V_{o2}	Channel Separation - note 4) 1kHz ≤ f ≤ 20kHZ		120		dB

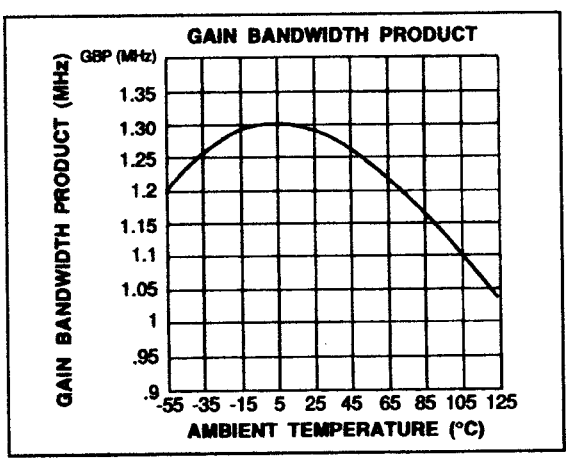
1. V_o = 1.4V, R_s = 0Ω, 5V < V_{CC}^+ < 30V, 0 < V_{ic} < V_{CC}^+ - 1.5V
2. The direction of the input current is out of the IC. This current is essentially constant, independent of the state of the output so no loading change exists on the input lines.
3. The input common-mode voltage of either input signal voltage should not be allowed to go negative by more than 0.3V. The upper end of the common-mode voltage range is V_{CC}^+ - 1.5V, but either or both inputs can go to +32V without damage.
4. Due to the proximity of external components insure that coupling is not originating via stray capacitance between these external parts. This typically can be detected as this type of capacitance increases at higher frequences.

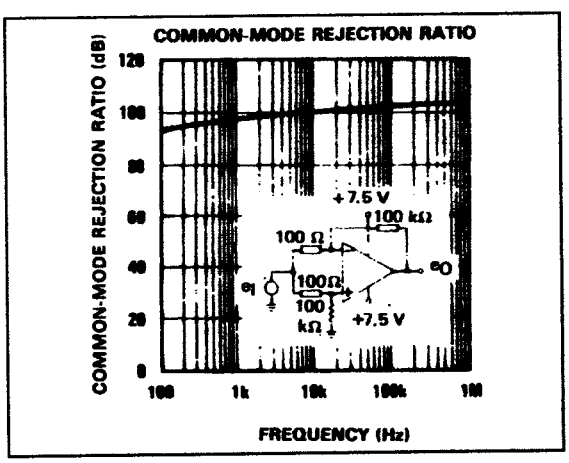




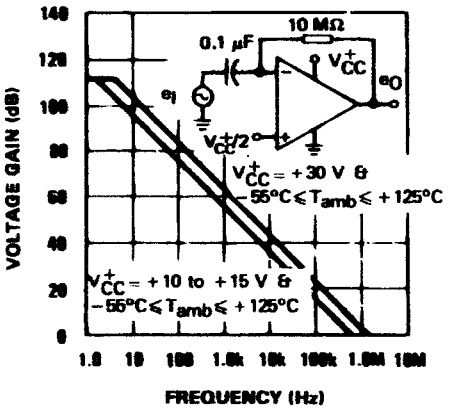




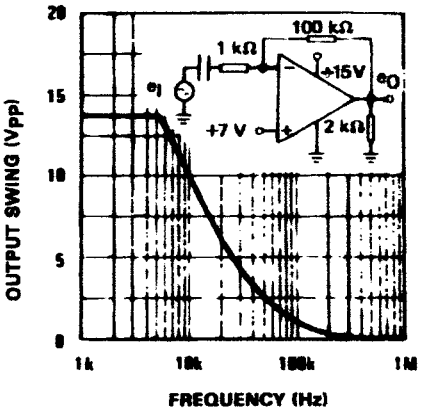




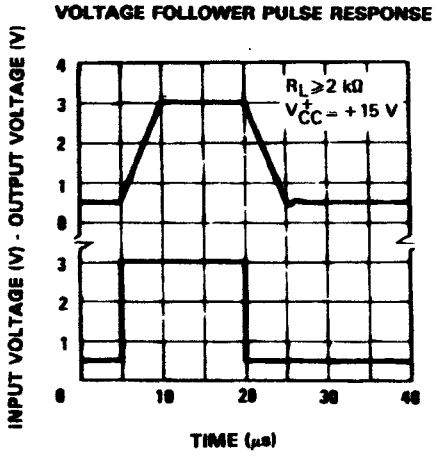
OPEN LOOP FREQUENCY RESPONSE



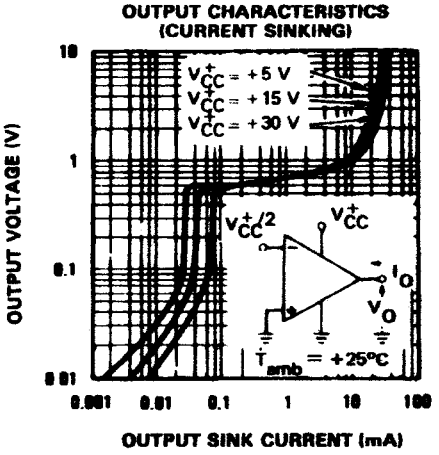
LARGE SIGNAL FREQUENCY RESPONSE



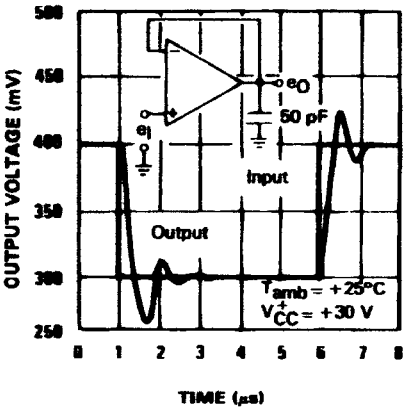
VOLTAGE FOLLOWER PULSE RESPONSE



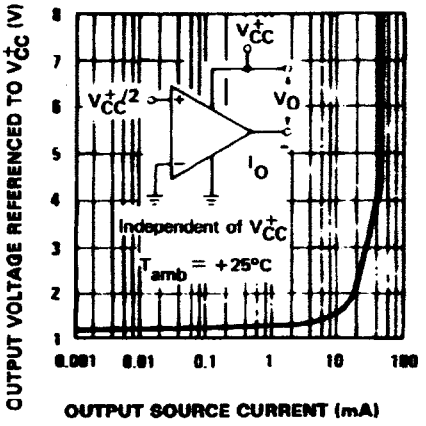
OUTPUT CHARACTERISTICS (CURRENT SINKING)

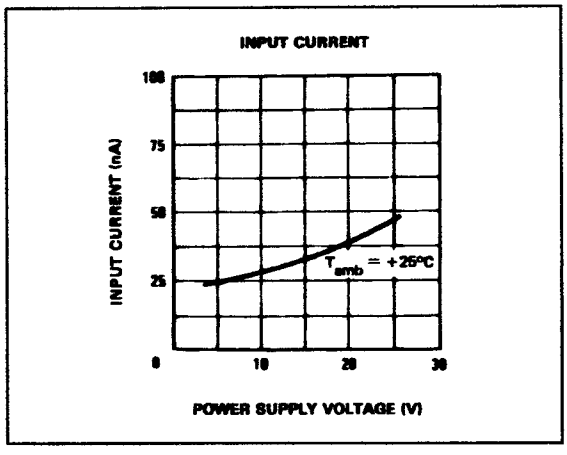


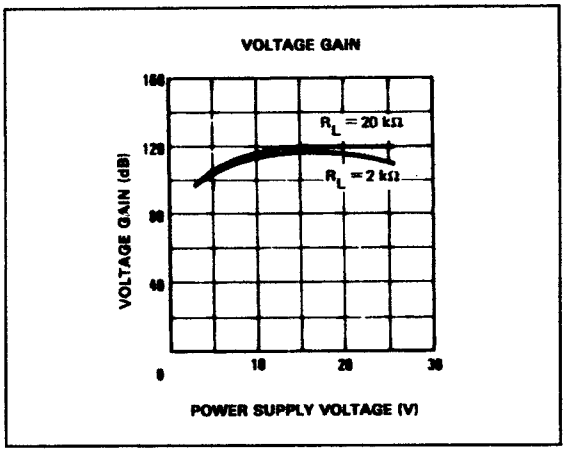
VOLTAGE FOLLOWER PULSE RESPONSE (SMALL SIGNAL)

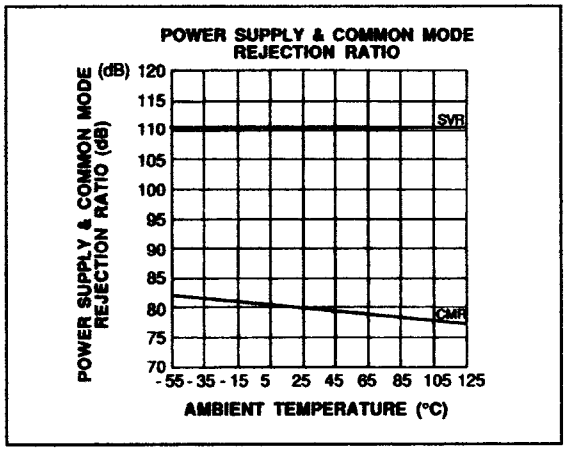


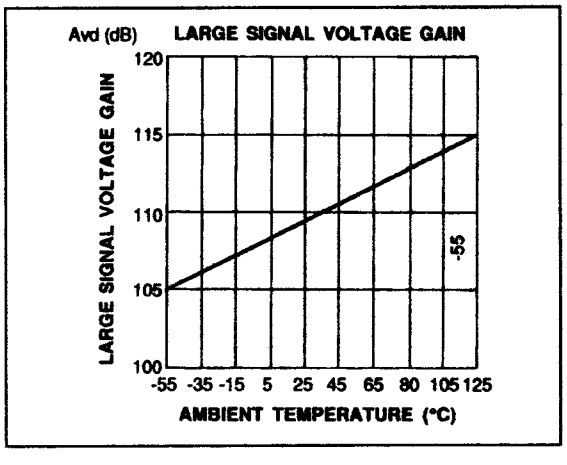
OUTPUT CHARACTERISTICS (CURRENT SOURCING)





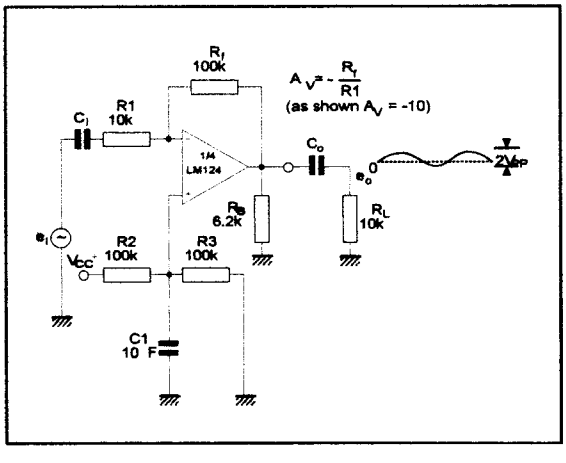




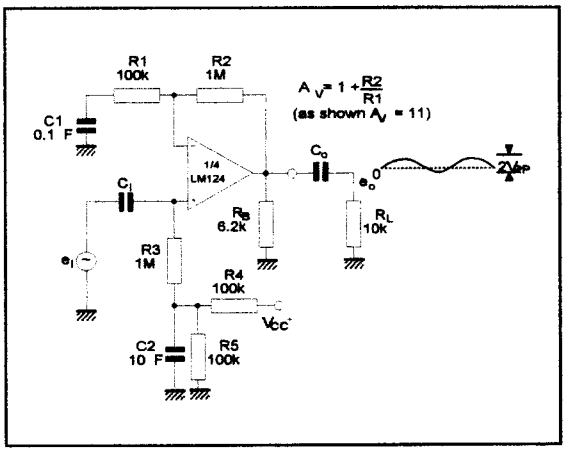


TYPICAL SINGLE - SUPPLY APPLICATIONS

AC COUPLED INVERTING AMPLIFIER

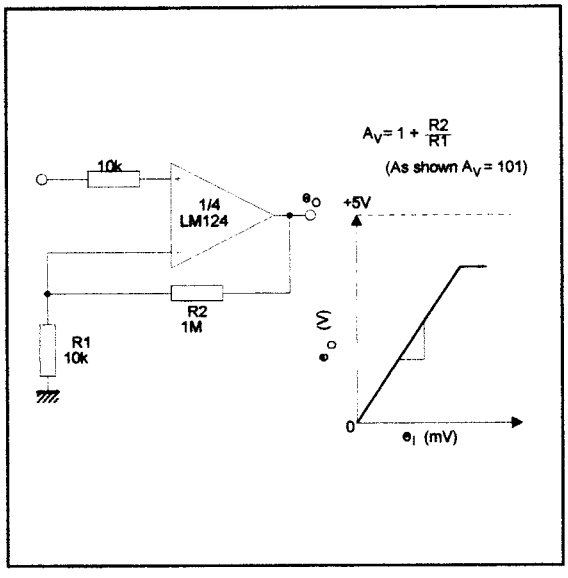


AC COUPLED NON INVERTING AMPLIFIER

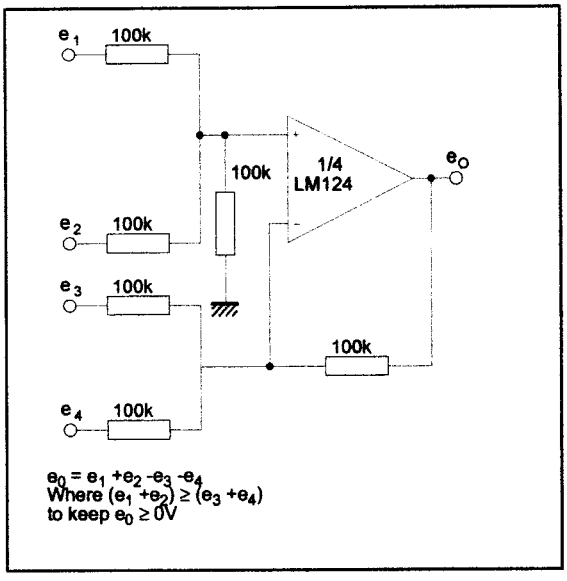


TYPICAL SINGLE - SUPPLY APPLICATIONS

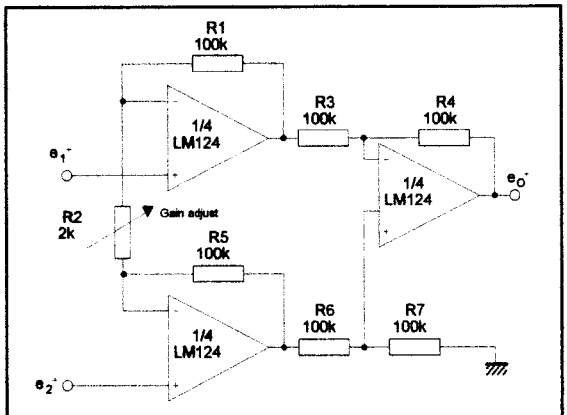
NON-INVERTING DC GAIN



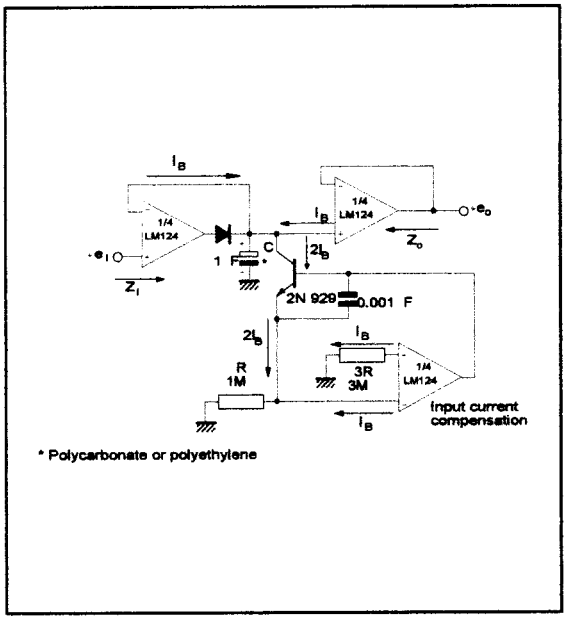
DC SUMMING AMPLIFIER



HIGH INPUT Z ADJUSTABLE GAIN DC INSTRUMENTATION AMPLIFIER

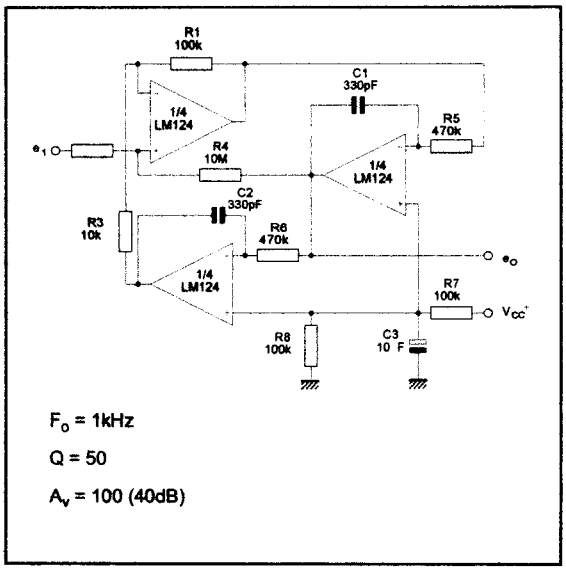


LOW DRIFT PEAK DETECTOR



TYPICAL SINGLE - SUPPLY APPLICATIONS

ACTIVER BANDPASS FILTER



F_o = 1kHz

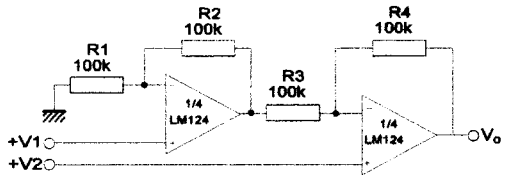
Q = 50

A_v = 100 (40dB)

HIGH INPUT Z, DC DIFFERENTIAL AMPLIFIER

For $\frac{R_1}{R_2} = \frac{R_4}{R_3}$

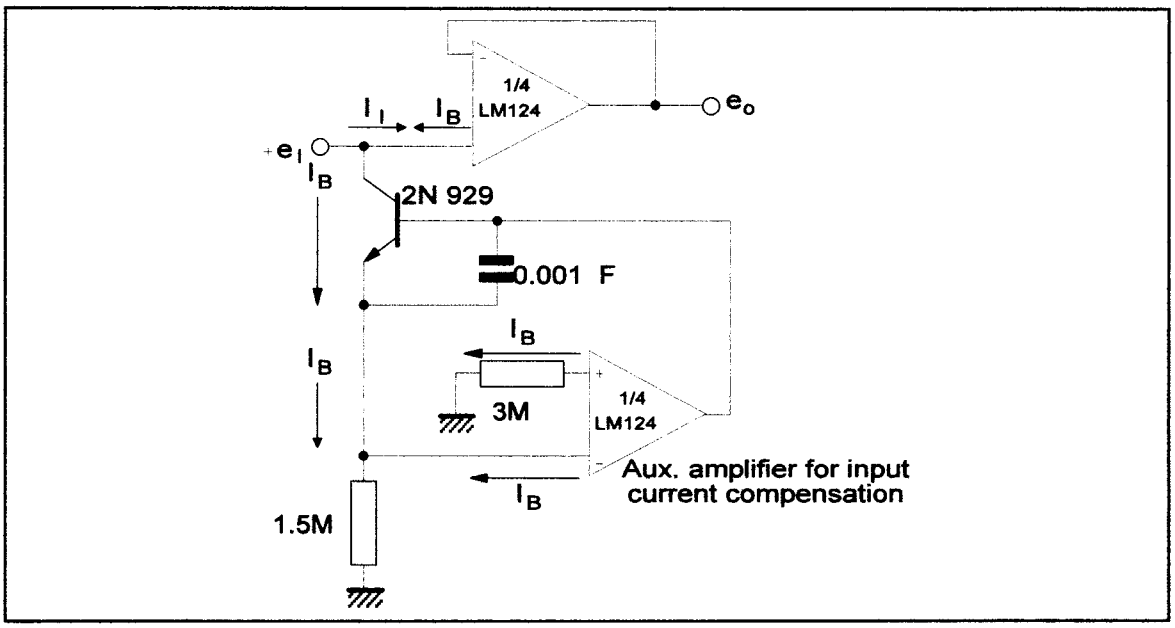
(CMRR depends on this resistor ratio match)



$e_0 \left(1 + \frac{R_4}{R_3}\right) (e_2 - e_1)$

As shown $e_0 = (e_2 - e_1)$

USING SYMETRICAL AMPLIFIERS TO REDUCE INPUT CURRENT (GENERAL CONCEPT)



MACROMODEL

**** Standard Linear Ics Macromodels, 1993.**

** CONNECTIONS :

* 1 INVERTING INPUT

* 2 NON-INVERTING INPUT

* 3 OUTPUT

* 4 POSITIVE POWER SUPPLY

* 5 NEGATIVE POWER SUPPLY

.SUBCKT LM124 1 3 2 4 5 (analog)

****

.MODEL MDTH D IS=1E-8 KF=3.104131E-15 CJO=10F

* INPUT STAGE

CIP 2 5 1.000000E-12

CIN 1 5 1.000000E-12

EIP 10 5 2 5 1

EIN 16 5 1 5 1

RIP 10 11 2.600000E+01

RIN 15 16 2.600000E+01

RIS 11 15 2.003862E+02

DIP 11 12 MDTH 400E-12

DIN 15 14 MDTH 400E-12

VOFP 12 13 DC 0

VOFN 13 14 DC 0

IPOL 13 5 1.000000E-05

CPS 11 15 3.783376E-09

DINN 17 13 MDTH 400E-12

VIN 17 5 0.000000e+00

DINR 15 18 MDTH 400E-12

VIP 4 18 2.000000E+00

FCP 4 5 VOFP 3.400000E+01

FCN 5 4 VOFN 3.400000E+01

FIBP 2 5 VOFN 2.000000E-03

FIBN 5 1 VOFP 2.000000E-03

* AMPLIFYING STAGE

FIP 5 19 VOFP 3.600000E+02

FIN 5 19 VOFN 3.600000E+02

RG1 19 5 3.652997E+06

RG2 19 4 3.652997E+06

CC 19 5 6.000000E-09

DOPM 19 22 MDTH 400E-12

DONM 21 19 MDTH 400E-12

HOPM 22 28 VOUT 7.500000E+03

VIPM 28 4 1.500000E+02

HONM 21 27 VOUT 7.500000E+03

VINM 5 27 1.500000E+02

EOUT 26 23 19 5 1

VOUT 23 5 0

ROUT 26 3 20

COUT 3 5 1.000000E-12

DOP 19 25 MDTH 400E-12

VOP 4 25 2.242230E+00

DON 24 19 MDTH 400E-12

VON 24 5 7.922301E-01

.ENDS

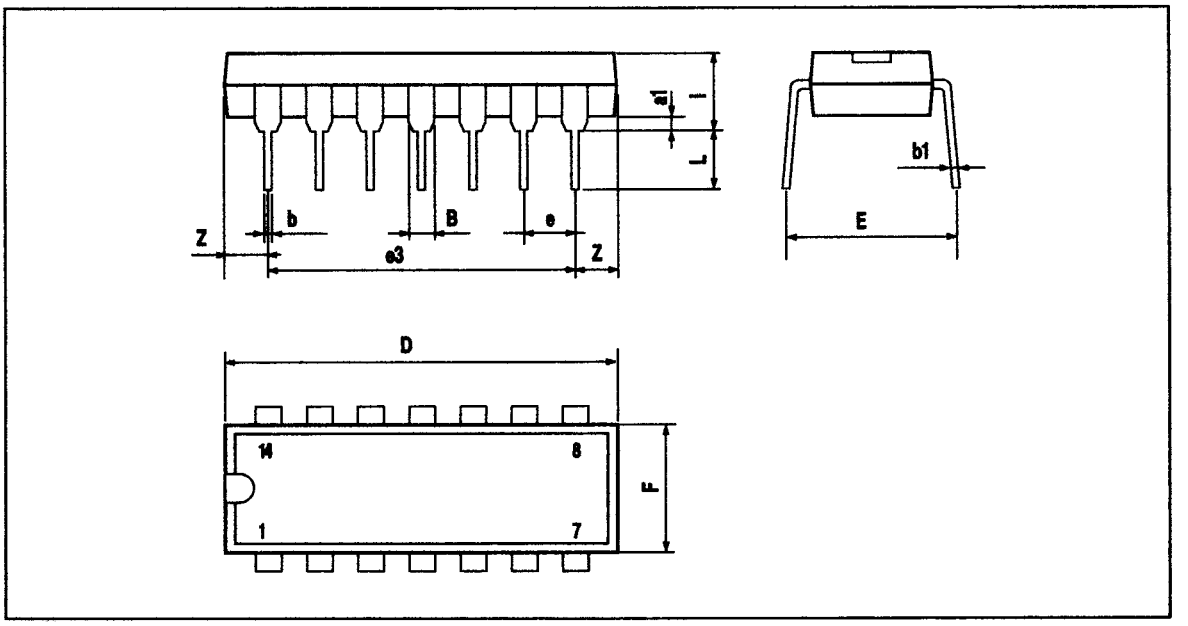
ELECTRICAL CHARACTERISTICS

V_{CC}^+ = +15V, V_{CC}^- = 0V, T_{amb} = 25°C (unless otherwise specified)

Symbol	Conditions	Value	Unit
V_{io}		0	mV
A_{vd}	R_L = 2kΩ	100	V/mV
I_{cc}	No load, per amplifier	350	µA
V_{icm}		-15 to +13.5	V
V_{OH}	R_L = 2kΩ (V_{CC}^+=15V)	+13.5	V
V_{OL}	R_L = 10kΩ	5	mV
I_{os}	V_o = +2V, V_{CC} = +15V	+40	mA
GBP	R_L = 2kΩ, C_L = 100pF	1.3	MHz
SR	R_L = 2kΩ, C_L = 100pF	0.4	V/µs

PACKAGE MECHANICAL DATA

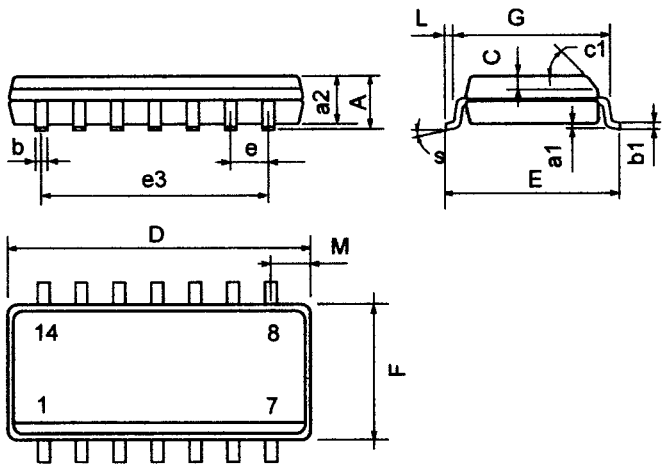
14 PINS - PLASTIC DIP



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
a1	0.51			0.020		
B	1.39		1.65	0.055		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		15.24			0.600	
F			7.1			0.280
i			5.1			0.201
L		3.3			0.130	
Z	1.27		2.54	0.050		0.100

PACKAGE MECHANICAL DATA

14 PINS - PLASTIC MICROPACKAGE (SO)

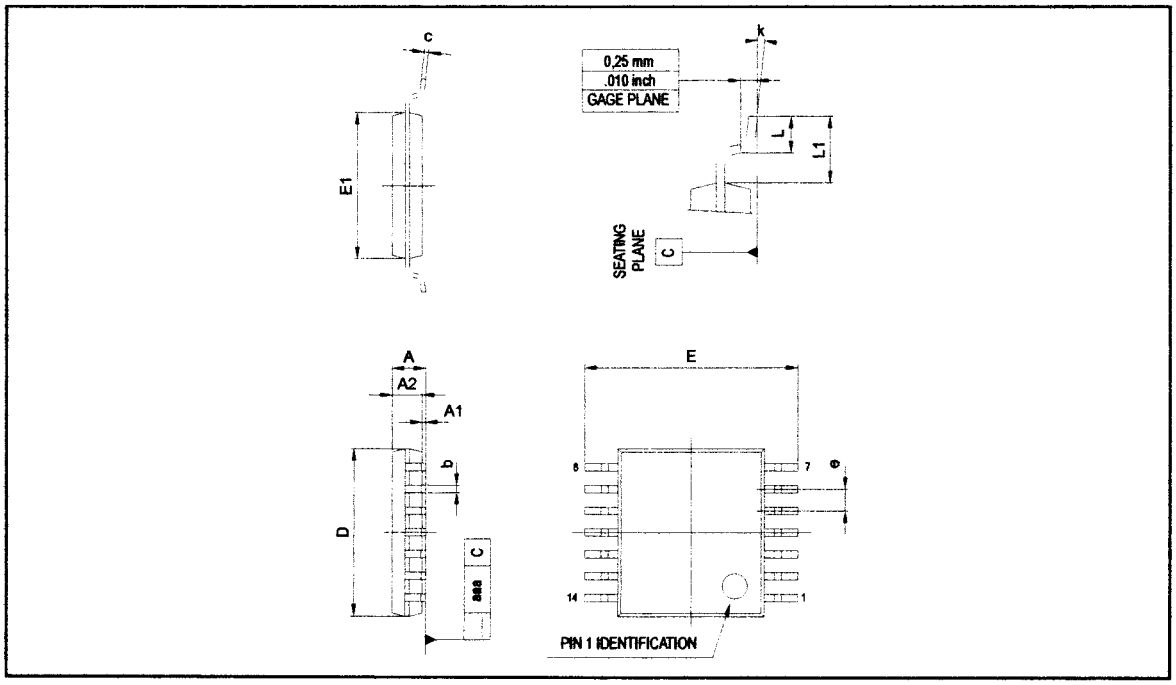


Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
a1	0.1		0.2	0.004		0.008
a2			1.6			0.063
b	0.35		0.46	0.014		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.020	
c1	45° (typ.)					
D (1)	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F (1)	3.8		4.0	0.150		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.020		0.050
M			0.68			0.027
S	8° (max.)					

Note : (1) D and F do not include mold flash or protrusions - Mold flash or protrusions shall not exceed 0.15mm (.066 inc) ONLY FOR DATA BOOK.

PACKAGE MECHANICAL DATA

14 PINS - THIN SHRINK SMALL OUTLINE PACKAGE (TSSOP)



Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.20			0.05
A1	0.05		0.15	0.01		0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.15
c	0.09		0.20	0.003		0.012
D	4.90	5.00	5.10	0.192	0.196	0.20
E		6.40			0.252	
E1	4.30	4.40	4.50	0.169	0.173	0.177
e		0.65			0.025	
k	0°		8°	0°		8°
L	0.450	0.600	0.750	0.018	0.024	0.030
L1		1.00			0.039	
aaa			0.100			0.004

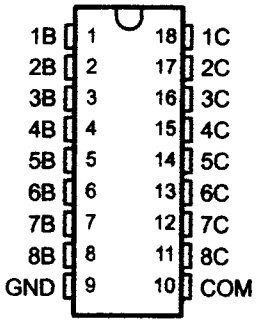
LAMPIRAN 1

ULN2803A
DARLINGTON TRANSISTOR ARRAY

SLRS049C – FEBRUARY1997 – REVISED AUGUST 2004

- **500-mA Rated Collector Current (Single Output)**
- **High-Voltage Outputs . . . 50 V**
- **Output Clamp Diodes**
- **Inputs Compatible With Various Types of Logic**
- **Relay Driver Applications**
- **Compatible with ULN2800A Series**

DW OR N PACKAGE
(TOP VIEW)



description/ordering information

The ULN2803A is a high-voltage, high-current Darlington transistor array. The device consists of eight npn Darlington pairs that feature high-voltage outputs with common-cathode clamp diodes for switching inductive loads. The collector-current rating of each Darlington pair is 500 mA. The Darlington pairs may be connected in parallel for higher current capability.

Applications include relay drivers, hammer drivers, lamp drivers, display drivers (LED and gas discharge), line drivers, and logic buffers. The ULN2803A has a 2.7-kΩ series base resistor for each Darlington pair for operation directly with TTL or 5-V CMOS devices.

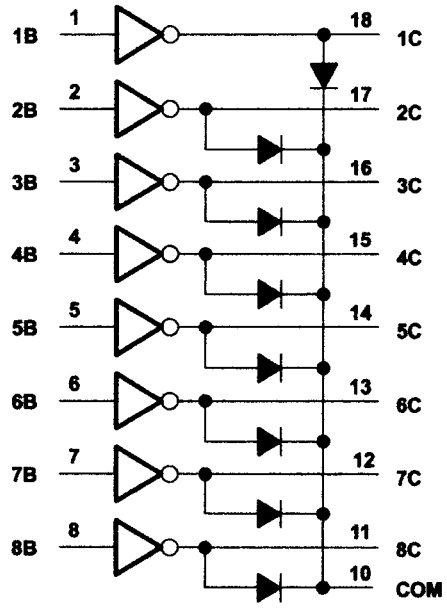
ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	PDIP (N)	Tube of 20	ULN2803AN	ULN2803AN
	SOIC (DW)	Tube of 40	ULN2803ADW	ULN2803A
		Reel of 2000	ULN2003ADWR	

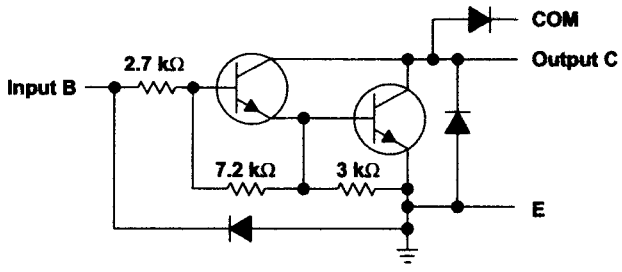
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

logic diagram



schematic (each Darlington pair)



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Collector-emitter voltage	50 V
Input voltage (see Note 1)	30 V
Continuous collector current	500 mA
Output clamp diode current	500 mA
Total substrate-terminal current	−2.5 A
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DW package	TBD°C/W
N package	TBD°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the emitter/substrate terminal GND.
2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{CEX}	Collector cutoff current	V_{CE} = 50 V, See Figure 1	I_I = 0,			50	µA
$I_{I(off)}$	Off-state input current	V_{CE} = 50 V, T_A = 70°C,	I_C = 500 µA, See Figure 2	50	65		µA
$I_{I(on)}$	Input current	V_I = 3.85 V,	See Figure 3		0.93	1.35	mA
$V_{I(on)}$	On-state input voltage	V_{CE} = 2 V, See Figure 4	I_C = 200 mA			2.4	V
			I_C = 250 mA			2.7	
			I_C = 300 mA			3	
$V_{CE(sat)}$	Collector-emitter saturation voltage	I_I = 250 µA, See Figure 5	I_C = 100 mA,		0.9	1.1	V
		I_I = 350 µA, See Figure 5	I_C = 200 mA,		1	1.3	
		I_I = 500 µA, See Figure 5	I_C = 350 mA,		1.3	1.6	
I_R	Clamp diode reverse current	V_R = 50 V,	See Figure 6			50	µA
V_F	Clamp diode forward voltage	I_F = 350 mA,	See Figure 7		1.7	2	V
C_i	Input capacitance	V_I = 0 V,	f = 1 MHz		15	25	pF

switching characteristics at 25°C free-air temperature

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	V_S = 50 V, C_L = 15 pF,	R_L = 163 Ω, See Figure 8		130		ns
t_{PHL}	Propagation delay time, high- to low-level output				20		
V_{OH}	High-level output voltage after switching	V_S = 50 V, See Figure 9	I_O = 300 mA,	V_S − 20			mV

PARAMETER MEASUREMENT INFORMATION

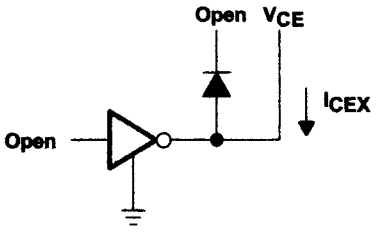


Figure 1. I_{CEX} Test Circuit

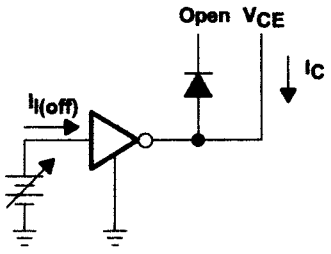


Figure 2. $I_{I(off)}$ Test Circuit

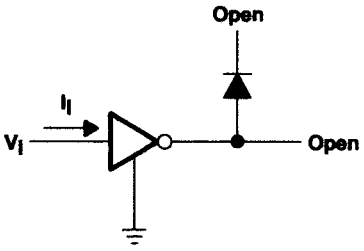


Figure 3. $I_{I(on)}$ Test Circuit

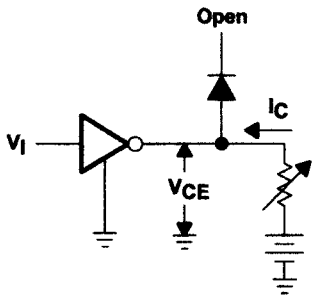


Figure 4. $V_{I(on)}$ Test Circuit

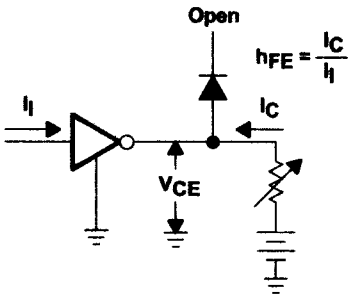


Figure 5. h_{FE}, $V_{CE(sat)}$ Test Circuit

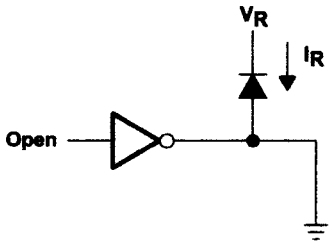


Figure 6. I_R Test Circuit

PARAMETER MEASUREMENT INFORMATION

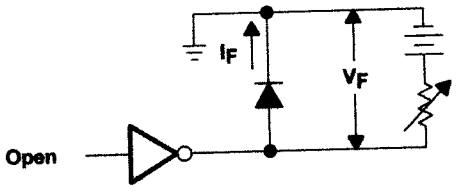
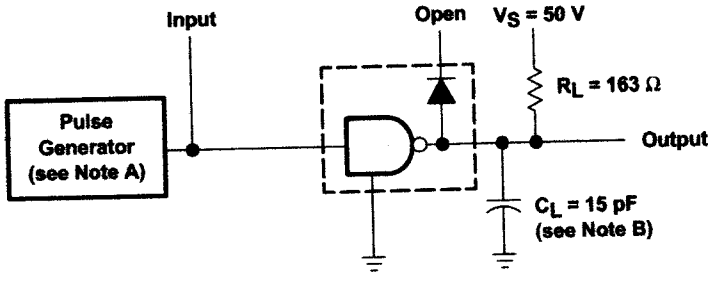
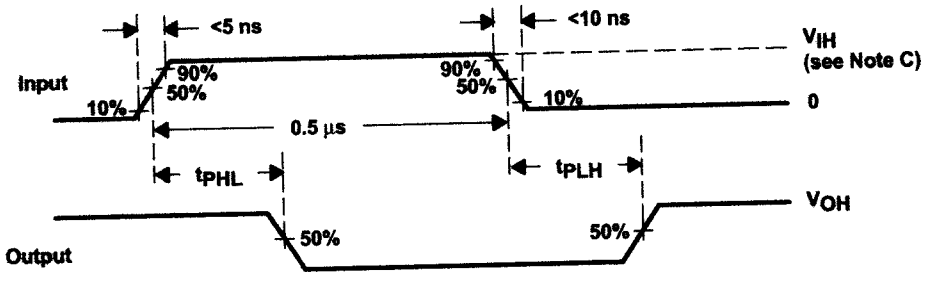


Figure 7. V_F Test Circuit



Test Circuit

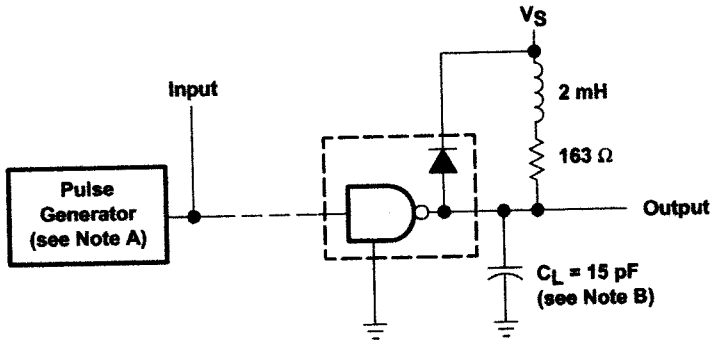


Voltage Waveforms

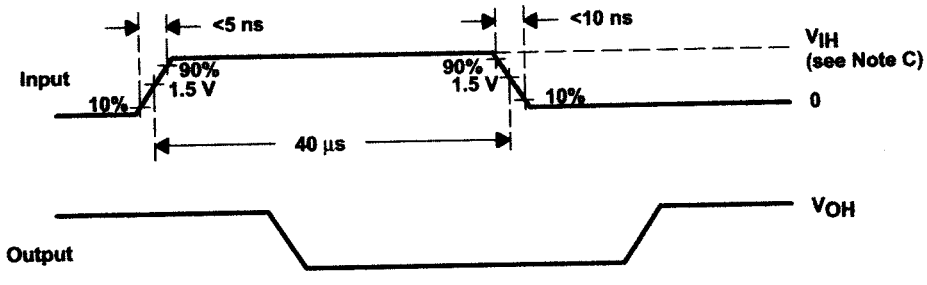
NOTES: A. The pulse generator has the following characteristics: PRR = 1 MHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.
C. V_{IH} = 3 V

Figure 8. Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION



Test Circuit



Voltage Waveforms

NOTES: A. The pulse generator has the following characteristics: PRR = 12.5 KHz, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.
C. V_{IH} = 3 V

Figure 9. Latch-Up Test

Features

- High-performance, Low-power Atmel® AVR® 8-bit Microcontroller
- Advanced RISC Architecture
  - 131 Powerful Instructions – Most Single-clock Cycle Execution
  - 32 x 8 General Purpose Working Registers
  - Fully Static Operation
  - Up to 16 MIPS Throughput at 16 MHz
  - On-chip 2-cycle Multiplier
- High Endurance Non-volatile Memory segments
  - 16 Kbytes of In-System Self-programmable Flash program memory
  - 512 Bytes EEPROM
  - 1 Kbyte Internal SRAM
  - Write/Erase Cycles: 10,000 Flash/100,000 EEPROM
  - Data retention: 20 years at 85°C/100 years at 25°C(1)
  - Optional Boot Code Section with Independent Lock Bits
    In-System Programming by On-chip Boot Program
    True Read-While-Write Operation
  - Programming Lock for Software Security
- JTAG (IEEE std. 1149.1 Compliant) Interface
  - Boundary-scan Capabilities According to the JTAG Standard
  - Extensive On-chip Debug Support
  - Programming of Flash, EEPROM, Fuses, and Lock Bits through the JTAG Interface
- Peripheral Features
  - Two 8-bit Timer/Counters with Separate Prescalers and Compare Modes
  - One 16-bit Timer/Counter with Separate Prescaler, Compare Mode, and Capture Mode
  - Real Time Counter with Separate Oscillator
  - Four PWM Channels
  - 8-channel, 10-bit ADC
    8 Single-ended Channels
    7 Differential Channels in TQFP Package Only
    2 Differential Channels with Programmable Gain at 1x, 10x, or 200x
  - Byte-oriented Two-wire Serial Interface
  - Programmable Serial USART
  - Master/Slave SPI Serial Interface
  - Programmable Watchdog Timer with Separate On-chip Oscillator
  - On-chip Analog Comparator
- Special Microcontroller Features
  - Power-on Reset and Programmable Brown-out Detection
  - Internal Calibrated RC Oscillator
  - External and Internal Interrupt Sources
  - Six Sleep Modes: Idle, ADC Noise Reduction, Power-save, Power-down, Standby and Extended Standby
- I/O and Packages
  - 32 Programmable I/O Lines
  - 40-pin PDIP, 44-lead TQFP, and 44-pad QFN/MLF
- Operating Voltages
  - 2.7V - 5.5V for ATmega16L
  - 4.5V - 5.5V for ATmega16
- Speed Grades
  - 0 - 8 MHz for ATmega16L
  - 0 - 16 MHz for ATmega16
- Power Consumption @ 1 MHz, 3V, and 25°C for ATmega16L
  - Active: 1.1 mA
  - Idle Mode: 0.35 mA
  - Power-down Mode: < 1 µA

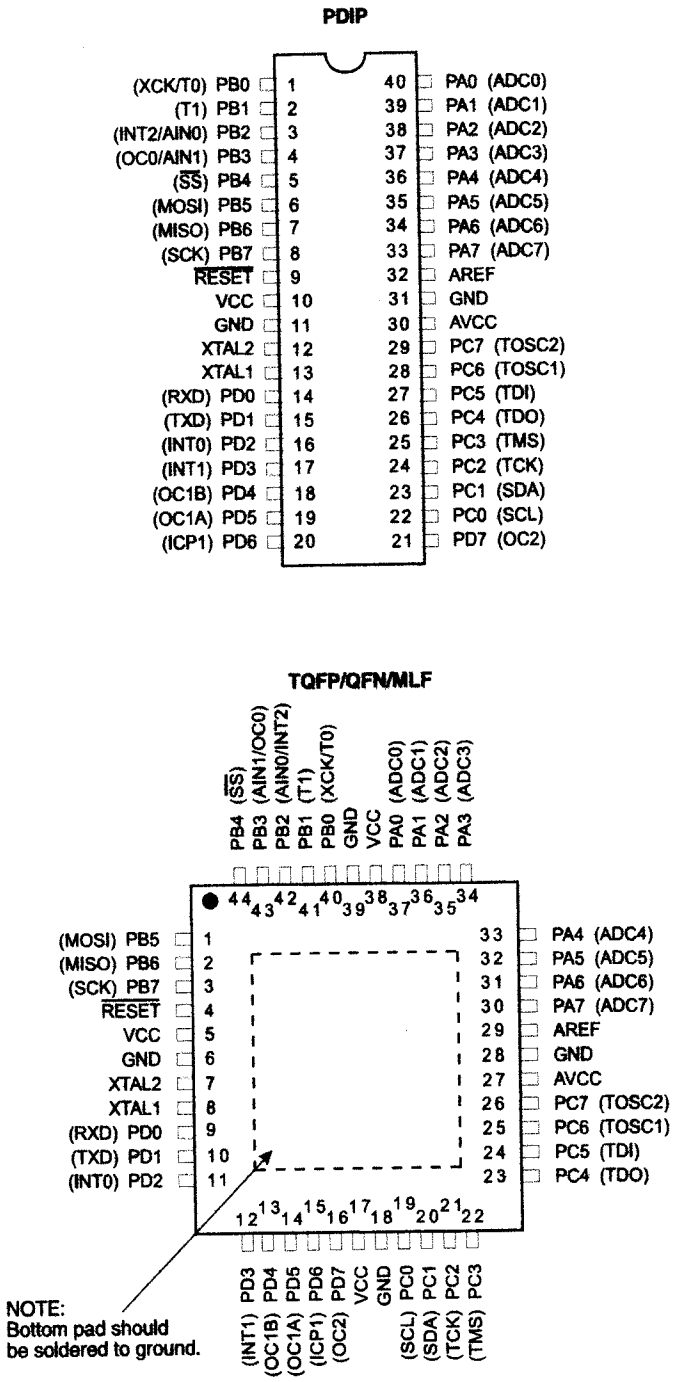
8-bit AVR® Microcontroller with 16K Bytes In-System Programmable Flash

ATmega16
ATmega16L

Rev. 2466T–AVR–07/10

Pin Configurations

Figure 1. Pinout ATmega16



Disclaimer

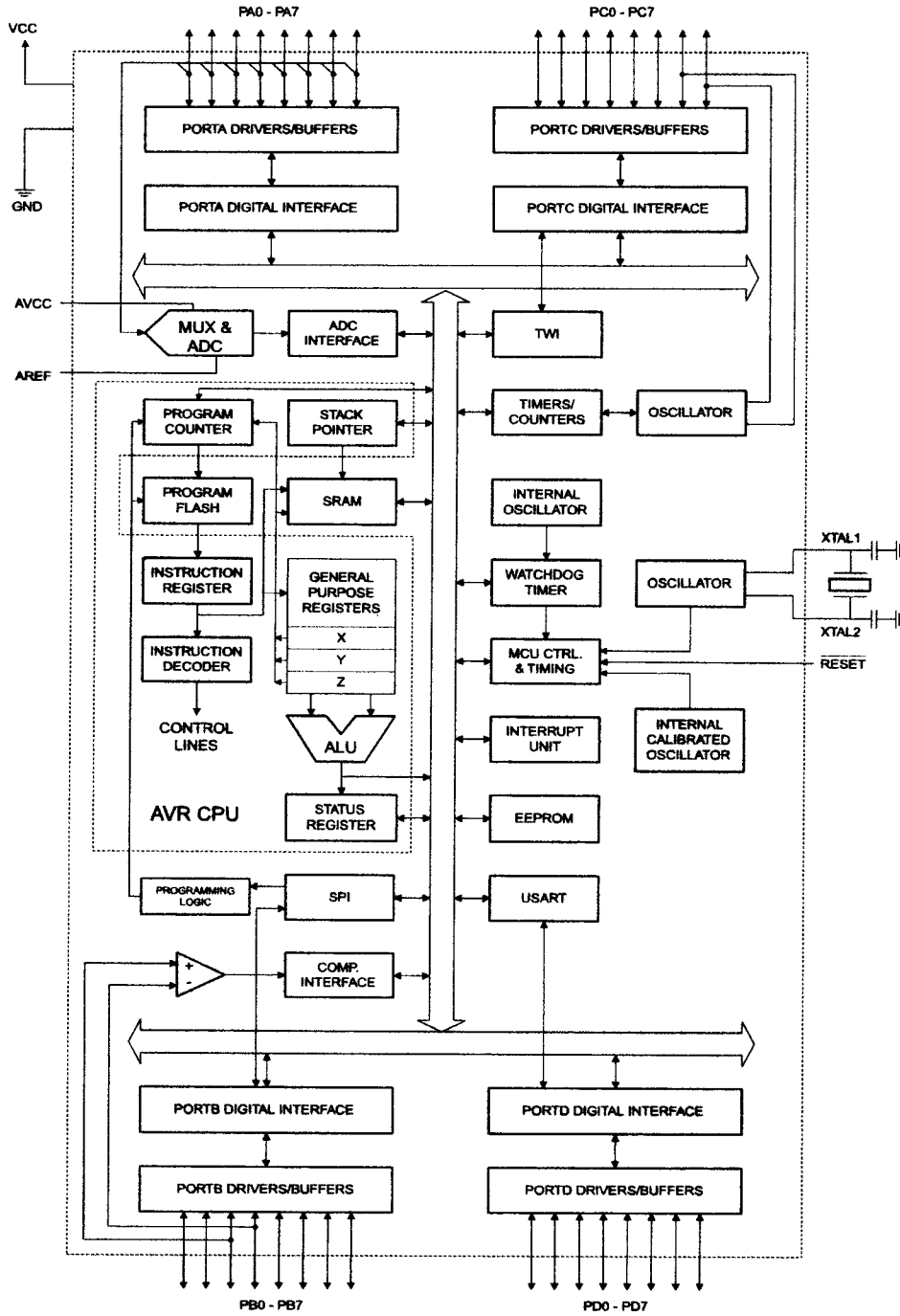
Typical values contained in this datasheet are based on simulations and characterization of other AVR microcontrollers manufactured on the same process technology. Min and Max values will be available after the device is characterized.

Overview

The ATmega16 is a low-power CMOS 8-bit microcontroller based on the AVR enhanced RISC architecture. By executing powerful instructions in a single clock cycle, the ATmega16 achieves throughputs approaching 1 MIPS per MHz allowing the system designer to optimize power consumption versus processing speed.

Block Diagram

Figure 2. Block Diagram



The AVR core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The ATmega16 provides the following features: 16 Kbytes of In-System Programmable Flash Program memory with Read-While-Write capabilities, 512 bytes EEPROM, 1 Kbyte SRAM, 32 general purpose I/O lines, 32 general purpose working registers, a JTAG interface for Boundary-scan, On-chip Debugging support and programming, three flexible Timer/Counters with compare modes, Internal and External Interrupts, a serial programmable USART, a byte oriented Two-wire Serial Interface, an 8-channel, 10-bit ADC with optional differential input stage with programmable gain (TQFP package only), a programmable Watchdog Timer with Internal Oscillator, an SPI serial port, and six software selectable power saving modes. The Idle mode stops the CPU while allowing the USART, Two-wire interface, A/D Converter, SRAM, Timer/Counters, SPI port, and interrupt system to continue functioning. The Power-down mode saves the register contents but freezes the Oscillator, disabling all other chip functions until the next External Interrupt or Hardware Reset. In Power-save mode, the Asynchronous Timer continues to run, allowing the user to maintain a timer base while the rest of the device is sleeping. The ADC Noise Reduction mode stops the CPU and all I/O modules except Asynchronous Timer and ADC, to minimize switching noise during ADC conversions. In Standby mode, the crystal/resonator Oscillator is running while the rest of the device is sleeping. This allows very fast start-up combined with low-power consumption. In Extended Standby mode, both the main Oscillator and the Asynchronous Timer continue to run.

The device is manufactured using Atmel's high density nonvolatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed in-system through an SPI serial interface, by a conventional nonvolatile memory programmer, or by an On-chip Boot program running on the AVR core. The boot program can use any interface to download the application program in the Application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable Flash on a monolithic chip, the Atmel ATmega16 is a powerful microcontroller that provides a highly-flexible and cost-effective solution to many embedded control applications.

The ATmega16 AVR is supported with a full suite of program and system development tools including: C compilers, macro assemblers, program debugger/simulators, in-circuit emulators, and evaluation kits.

Pin Descriptions

VCC Digital supply voltage.

GND Ground.

Port A (PA7..PA0) Port A serves as the analog inputs to the A/D Converter.

Port A also serves as an 8-bit bi-directional I/O port, if the A/D Converter is not used. Port pins can provide internal pull-up resistors (selected for each bit). The Port A output buffers have symmetrical drive characteristics with both high sink and source capability. When pins PA0 to PA7 are used as inputs and are externally pulled low, they will source current if the internal pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B (PB7..PB0) Port B is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port B output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B also serves the functions of various special features of the ATmega16 as listed on page 58.

Port C (PC7..PC0) Port C is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port C output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port C pins that are externally pulled low will source current if the pull-up resistors are activated. The Port C pins are tri-stated when a reset condition becomes active, even if the clock is not running. If the JTAG interface is enabled, the pull-up resistors on pins PC5(TDI), PC3(TMS) and PC2(TCK) will be activated even if a reset occurs.

Port C also serves the functions of the JTAG interface and other special features of the ATmega16 as listed on page 61.

Port D (PD7..PD0) Port D is an 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). The Port D output buffers have symmetrical drive characteristics with both high sink and source capability. As inputs, Port D pins that are externally pulled low will source current if the pull-up resistors are activated. The Port D pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port D also serves the functions of various special features of the ATmega16 as listed on page 63.

$\overline{\text{RESET}}$ Reset Input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running. The minimum pulse length is given in Table 15 on page 38. Shorter pulses are not guaranteed to generate a reset.

XTAL1 Input to the inverting Oscillator amplifier and input to the internal clock operating circuit.

XTAL2 Output from the inverting Oscillator amplifier.

AVCC AVCC is the supply voltage pin for Port A and the A/D Converter. It should be externally connected to V_{CC}, even if the ADC is not used. If the ADC is used, it should be connected to V_{CC} through a low-pass filter.

AREF AREF is the analog reference pin for the A/D Converter.

Resources

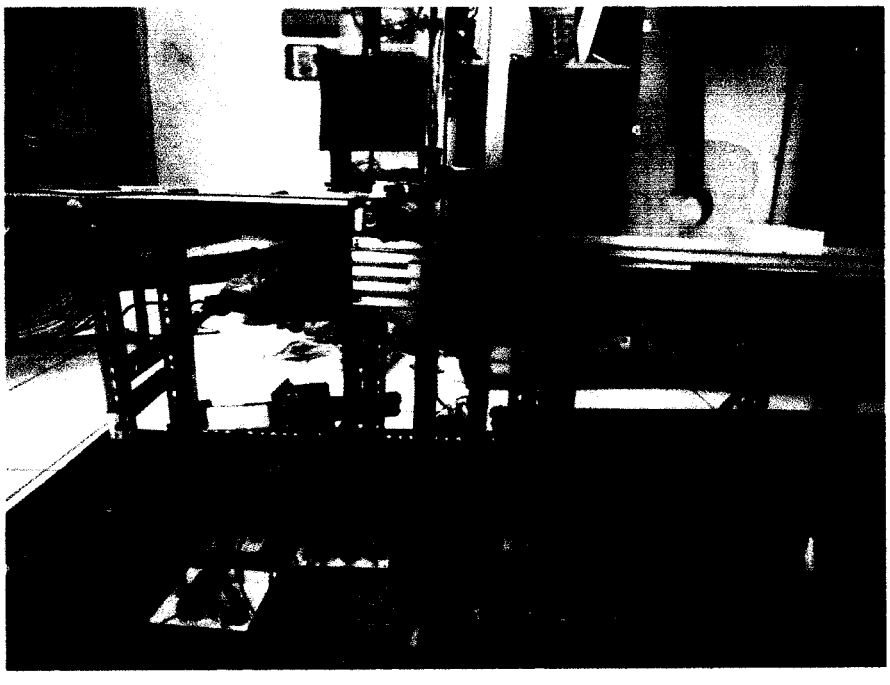
A comprehensive set of development tools, application notes and datasheets are available for download on http://www.atmel.com/avr.

Data Retention

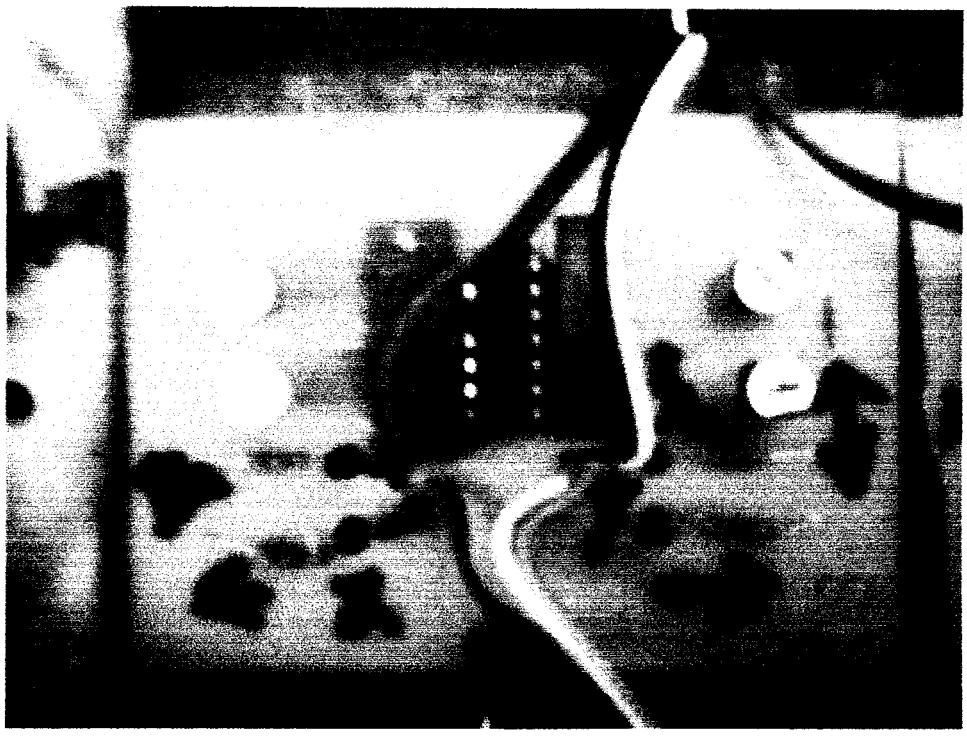
Reliability Qualification results show that the projected data retention failure rate is much less than 1 PPM over 20 years at 85°C or 100 years at 25°C.

LAMPIRAN 2

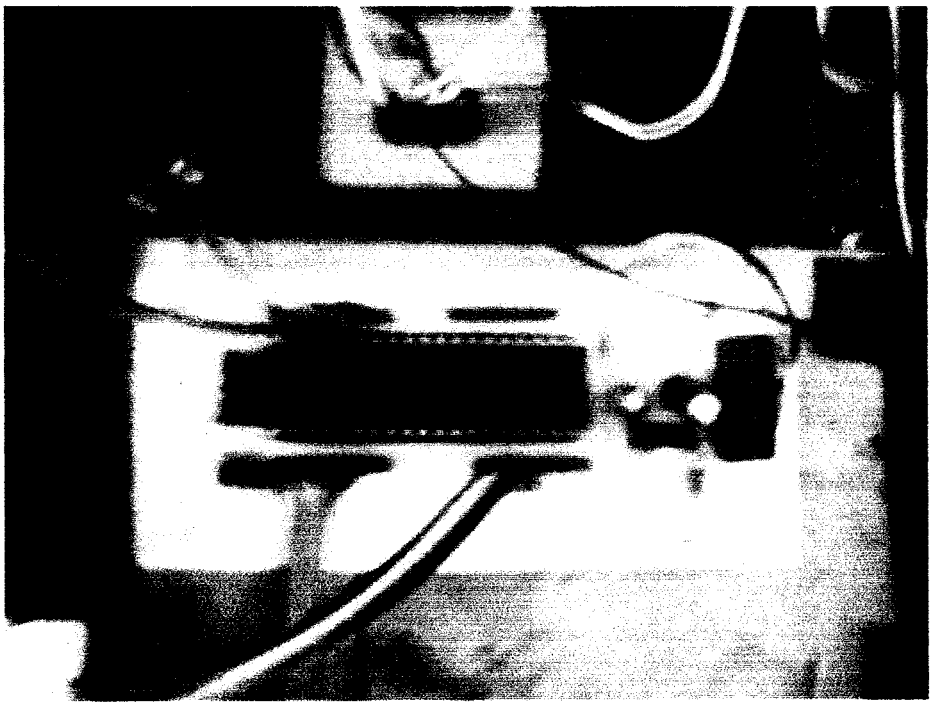
Gambar tampak atas



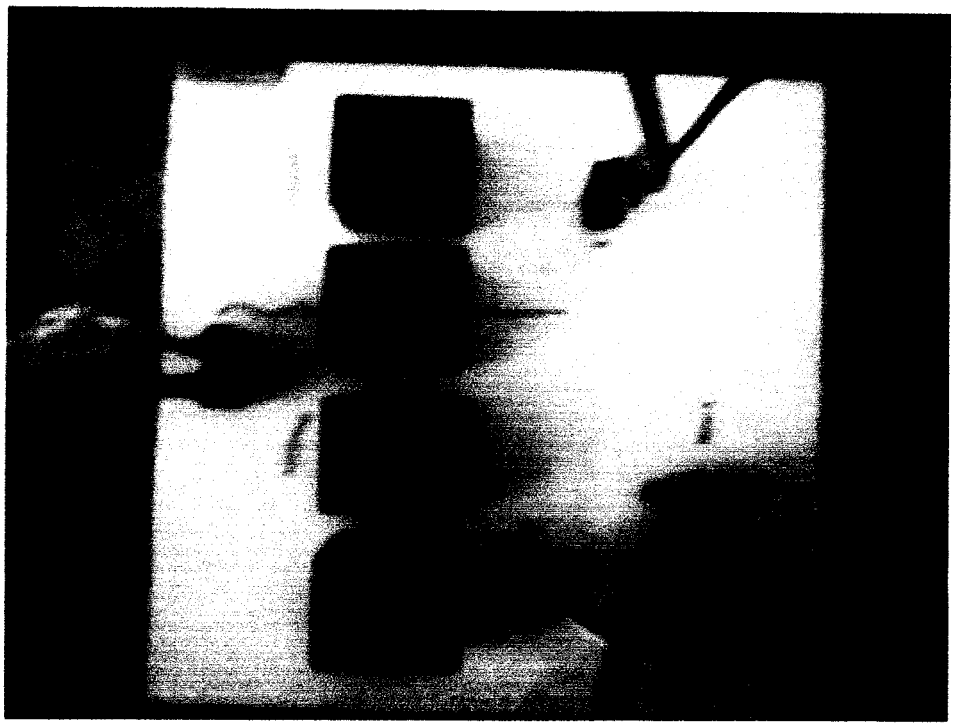
Gambar tampak samping



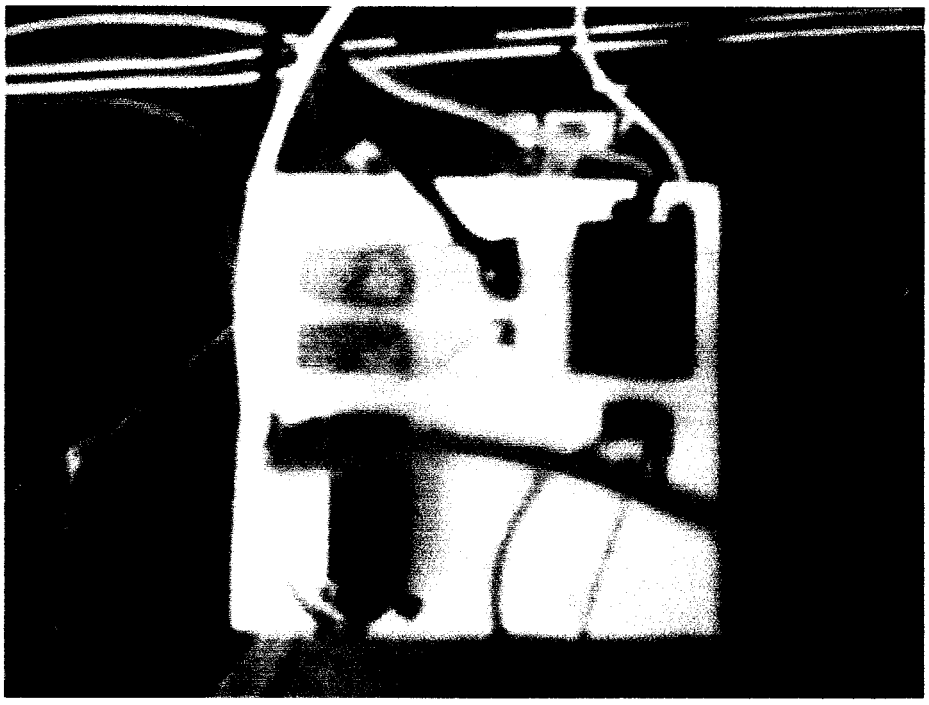
Gambar komparator



Gambar minimum sitem



Gambar relay lengan robot dan pendorong



Gambar relay segitiga dan konveyor